

Title (en)

METHOD FOR PREPARING AN ELECTROPLATED PRODUCT BY DEPOSITING AN UNDERLAYER, DIFFUSION BARRIER LAYER AND TOP LAYER ON THE SURFACE OF A SUBSTRATE AND SUCH PREPARED ELECTROPLATED PRODUCT

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES ELEKTROPLATTIERTEN PRODUKTES DURCH ABSCHIEDUNG EINER UNTERSCHICHT, DIFFUSIONSBARRIERESCHICHT UND DECKSCHICHT AUF DER OBERFLÄCHE

Title (fr)

PROCÉDÉ DE PRÉPARATION D'UN PRODUIT ÉLECTRODÉPOSÉ PAR DÉPÔT D'UNE SOUS-COUCHE, D'UNE COUCHE BARRIÈRE DE DIFFUSION ET D'UNE COUCHE SUPÉRIEURE SUR LA SURFACE D'UN SUBSTRAT ET PRODUIT ÉLECTRODÉPOSÉ AINSI PRÉPARÉ

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Abstract (en)

[origin: EP4001472A1] The present invention refers to a method for preparing an electroplated product by depositing an underlayer, a barrier diffusion layer and a top layer on a surface of a substrate comprising or consisting of copper or a copper or copper alloy layer wherein the underlayer comprises or consists of a precious metal selected from the group consisting of Au, Ag, Pd, Rh, Ru, Pt and alloys thereof and the top layer comprises or consists of a precious metal selected from the group consisting of Au, Ag, Pd, Rh, Ru, Pt and alloys thereof. The underlayer and the top layer are separated by a barrier diffusion layer comprising or consisting of Indium or an alloy of Indium. This barrier layer prevents the interdiffusion between the underlayer and the top layer. Moreover, the present invention also refers to an electroplated product obtainable by such a method.

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